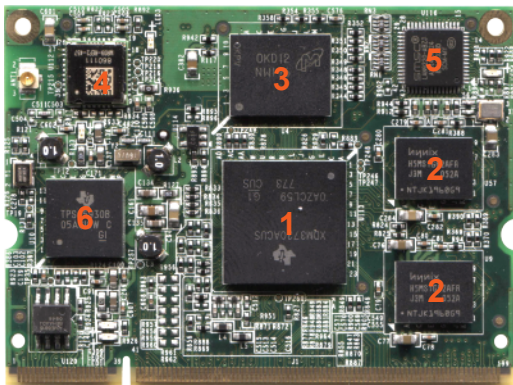


# TDM-3730

## System on Module



TI Sitara DM3730 1GHz application processor with ARM Cortex-A8 CPU, and POWERVR SGX 530 for 2D and 3D graphics acceleration.

200 pin SO-DIMM connector carrying LAN, USB, UART, SPI, I<sup>2</sup>C, LCD, Camera signals making the TDM-3730 ideal for demanding multimedia application.



### System

CPU	TI Sitara 3730 @ 1GHz (1)
DSP core	TMS320C64x+™ @ 800MHz
PMIC	TPS65930 (6)
Memory	512 MB Low power mobile DDR (2) optional configurations upto 1GB
Storage	512 MB NAND Flash (3)
Wireless LAN	Marvell 8686 802.11b/g (4)
Network	SMSC LAN 9220 (5)
Supported OS	Linux 2.6.x, Windows Embedded Compact 7 and Android

### Interfaces

Connectors	200 pin SO-DIMM with SPI, UART, USB host, USB OTG/ client, I <sup>2</sup> C, PWM lines, 1-wire, MMC lines, A/D lines, camera, audio in/out, mic keypad, S-Video, Display, LAN
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### Graphic Capabilities

Chipset	POWERVR SGX 530
API support	20Mpolys/s, up to 720p resolution OpenGL 2.0, OpenGL ES 1.1, OpenVG 1.0

### Power

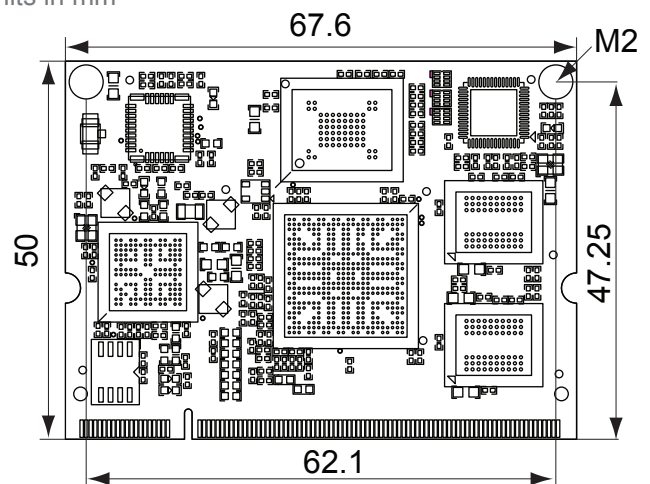
Power consumption	<2.0 Watt with Wireless enabled
Standby	<50 mWatt
Input power	5V

### Environmental and Mechanical

Temperature	Commercial: 0° to 70° C Extended: -20° to 70° C (no wifi) Industrial: -40° to 85° C (no wifi)
Humidity	10-90%
Dimensions	67.6x 50x 3.4 mm (2½x 2x ¼ inch)
MTBF	>100,000 hours
Weight	12 grams
Shock	50G / 25ms
Vibration	20G / 0-600 Hz

### Dimensions

units in mm



### Order Information

TDM-3730	DM3730 System on Module
TDM-3730-i	DM3730 System on module with industrial temperature specifications (MOQ's apply)
TDM-3730W	DM3730 System on Module with Wireless LAN 802.11 b/g

Development kits available

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